

The Eighth Asia International Symposium on Mechatronics (AISM2021)

16-19 December, 2021, Liuzhou, China

<http://aism2021.org>

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Paper Submission

Manuscripts will be submitted as a PDF file and the length of Final Manuscripts must be within 6 pages using our template.

Before submission, please carefully confirm the submission guideline in the Paper Submission page on the AISM2021 web site. <http://aism2021.org>

Awards

AISM2021 Best Paper Award and Best Student Paper Award will present to the author(s) and young student author(s) of the excellent papers respectively.

Technical Co-Sponsors

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About AISM2021

Mechatronics is an ever-widening field involving actuators/sensors, electronics/mechanics, controls, system design/integration, and beyond. The aim of the symposium is to promote the research, development and application in this field. Following the success of the first, second, third, fourth, fifth, sixth and seventh AISM, the eighth AISM will be held in Seoul, Korea, this symposium will bring together researchers and engineers in this multidisciplinary field to simulate new ideas, to share knowledge in practical problems and solutions, as well as to facilitate cooperation for the future.

The scope of the symposium will cover the following subjects but are not limited:

A. Electromechanical Coupling of Electronic Equipment

- A1. Multiple-field couple modeling A2. Electro-mechanical coupling analysis
A3. Multidisciplinary optimization

B. Mechatronics Design

- B1. Engineering machinery design B2. Industrial design B3. Electronic packaging design
B4. Structure-performance-function integrated robot design B5. Flexible electronic design

C. Advanced Manufacturing Technology of Electronic Machinery

- C1. Additive manufacturing C2. Virtual manufacturing C3. Microsystem manufacturing
C4. Intelligent manufacturing C5. Electronic packaging

D. Environmental Adaptability Design of Electronic Equipment

- D1. Thermal design D2. Vibration and control
D3. Electromagnetic compatibility design D4. Reliability engineering

E. Sensing and Measurement

- E1. Sensing and measurement in electromechanical systems E2. Nondestructive testing and evaluation
E3. Machine vision and image processing E4. Intelligent sensing and control

F. Micro-nano Electromechanical System

- F1. Micro and nano mechatronics F2. Micro-sensors and micro-actuators
F3. Mechatronics in MEMS F4. Microfluidic technology

G. Hot spots and trends on electronic equipment intelligent research

- G1. Space solar power station G2. Wireless power transmission technology
G3. Smart cars and internet of vehicles G4. Energy internet technology
G5. Application technology of artificial intelligence in electromechanical and energy cross field

H. Hot spots and trends on combination research of medicine and engineering

- H1. Biological manufacturing H2. Production of bio-mechatronics intelligent equipment or systems
H3. Biosensing technology

Important Dates

July 22, 2021

Submission of long abstract or manuscript

Aug. 31, 2021

Paper submission deadline

Oct. 10, 2021

Notification of acceptance

